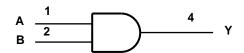


Pin Descriptions

Pin Name	Description			
Α	Data Input			
В	Data Input			
GND	Ground			
Y	Data Output			
Vcc	Supply Voltage			

Logic Diagram



Function Table

Inp	Output	
Α	В	Υ
Н	Н	Н
L	Х	L
Х	L	L



Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 4)

Symbol		Parameter	Min	Max	Unit	
\/	On a ratio a Valta as	Operating	1.4	5.5	V	
V_{CC}	Operating Voltage	Data retention only	1.2		V	
		V _{CC} = 1.4 V to 1.95 V	0.65 X V _{CC}			
\/	High lovel Input Voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		M	
V_{IH}	High-level Input Voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		V	
		V _{CC} = 4.5 V to 5.5 V	0.7 X V _{CC}			
		V _{CC} = 1.4 V to 1.95 V		0.35 X V _{CC}		
W	L our lovel input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V	
		V _{CC} = 4.5 V to 5.5 V		0.3 X V _{CC}		
Vı	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	V _{CC}	V	
		Vcc=1.4 V		-3		
	High level output output	V _{CC} = 1.65 V		-4	mA	
		V _{CC} = 2.3 V		-8		
I _{OH}	High-level output current	V _{CC} = 3 V		-16		
				-24		
		V _{CC} = 4.5 V		-32		
		Vcc=1.4 V		3		
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		8	mΑ	
I _{OL}	Low-level output current			16		
		$V_{CC} = 3 V$		24		
		V _{CC} = 4.5 V		32		
		V _{CC} = 1.4 to 3V		20		
Δt/ΔV	Input transition rise or fall	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
	rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5	112, 1	
T _A	Operating free-air temperature		-40	85	°C	

Note: 4. Unused inputs should be held at Vcc or Ground.



Electrical Characteristics (All typical values are at Vcc = 3.3V, T_A = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit	
		I _{OH} = -100μA	1.4 V to 5.5V	V _{CC} - 0.1				
		$I_{OH} = -3mA$	1.4 V	1.05				
		$I_{OH} = -4mA$	1.65 V	1.2				
V_{OH}	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V	
	Voltage	I _{OH} = -16mA	3 V	2.4				
		$I_{OH} = -24mA$	3 V	2.3				
		$I_{OH} = -32mA$	4.5 V	3.8				
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1		
		$I_{OL} = 3mA$	1.4 V			.4		
		I _{OL} = 4mA	1.65 V			0.45		
V_{OL}	V _{OL} High-level Input Voltage	$I_{OL} = 8mA$	2.3V			0.3	V	
		I _{OL} = 16mA	3 V			0.4		
		$I_{OL} = 24mA$	3 V			0.55		
		$I_{OL} = 32mA$	4.5			0.55		
l _l	Input Current	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μΑ	
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 5.5V$	0			± 10	μΑ	
I _{CC}	Supply Current	$V_1 = 5.5V$ of GND $I_0=0$	1.4 V to 5.5V			10	μΑ	
ΔI _{CC}	Additional Supply Current	One input at V _{CC} – 0.6 V Other inputs at V _{CC} or GND	3 V to 5.5V			500	μA	
Ci	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	3.3		3.5		pF	
	T. 15	SOT25	(Note 5)		204			
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT353	(Note 5)		371		°C/W	
		DFN1410	(Note 5)		430			
		SOT25	(Note 5)		52			
θ_{JC}	θ _{JC} Thermal Resistance	SOT353	(Note 5)		143		°C/W	
	Junction-to-Case	DFN1410	(Note 5)		190			

Note: 5. Test condition for SOT25, SOT353, and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		: 3.3 V).3V		= 5 V).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	1.5	7.2	1.0	5	0.5	3.5	0.6	2.9	0.7	2.9	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		: 3.3 V).3V		= 5 V).5V	Unit
	(Input) (OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	O	
t_{pd}	A or B	Y	2.4	8	1.6	5.6	0.8	4.4	0.8	3.6	0.9	3.6	ns

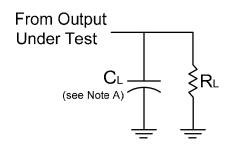
Operating Characteristics

 $T_A = 25$ °C

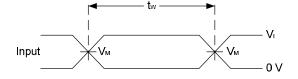
P	arameter	Test Conditions	Vcc = 1.5 V TYP	Vcc = 1.8 V TYP	Vcc = 2.5 V TYP	Vcc = 3.3 V	Vcc = 5 V	Unit
$C_{\sf pd}$	Power dissipation capacitance	f = 10 MHz	21	21	24	26	31	pF



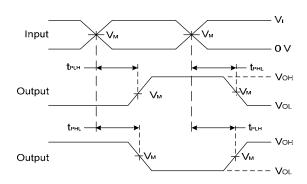
Parameter Measurement Information



Vcc	In	Inputs		6	В
VCC	Vı	t _r /t _f	V _M	CL	R _L
1.5V±0.1V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
1.8V±0.15V	V _{cc}	≤2ns	V _{CC} /2	15pF	1ΜΩ
2.5V±0.2V	V _{cc}	≤2ns	V _{CC} /2	15pF	1ΜΩ
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ
5V±0.5V	V _{cc}	≤2.5ns	V _{CC} /2	15pF	1ΜΩ



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

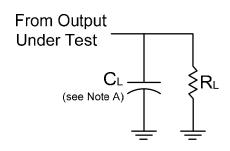
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

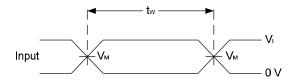
Figure 1. Load Circuit and Voltage Waveforms



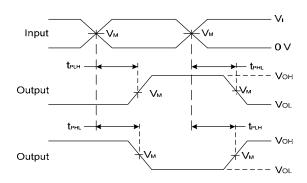
Parameter Measurement Information (Continued)



Vcc	Inp	outs	V _M	CL	R_L
	Vı	t _r /t _f	- IVI	OL.	
1.5V±0.1V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ
2.5V±0.2V	V _{cc}	≤2ns	V _{CC} /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.

C. Inputs are measured separately one transition per measurement.

D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

Figure 2. Load Circuit and Voltage Waveforms

(P),



SINGLE 2 INPUT POSITIVE AND GATE

Ordering Information

T4LVCE1G 08 XXX - 7

Logic Device Function Package Packing

74: Logic Prefix 08: 2-Input W5: SOT25 7: Tape & Reel

LVCE: 1.4 to 5.5V

Family 1G : One gate AND-Gate SE: SOT353 FZ4: DFN1410

Device	Package	Packaging	7" Tape a	nd Reel
Device	Code	(Note 5)	Quantity	Part Number Suffix
74LVCE1G08W5-7	W6	SOT25	3000/Tape & Reel	-7
74LVCE1G08SE-7	SE	SOT353	3000/Tape & Reel	-7
74LVCF1G08F74-7	F74	DFN1410	5000/Tane & Reel	-7

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Marking Information

(1) SOT25 and SOT353

(Top View)

5 4 XX Y W X

2

3

1

XX: Identification code

Y: Year 0~9

 $\overline{\underline{W}}$: Week : A $^{\sim}$ Z : 1 $^{\sim}$ 26 week;

a~z: 27~52 week; z represents

52 and 53 week

X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G08W5	SOT25	PV
74LVCE1G08SE	SOT353	PU

(2) DFN1410H4-6

(Top View)

 XX: Identification Code

Y: Year: 0~9

<u>W</u>: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

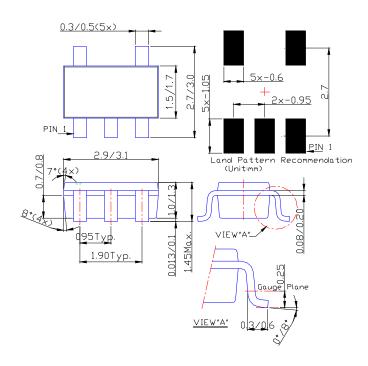
52 and 53 week \underline{X} : A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G08FZ4	DFN1410	PV

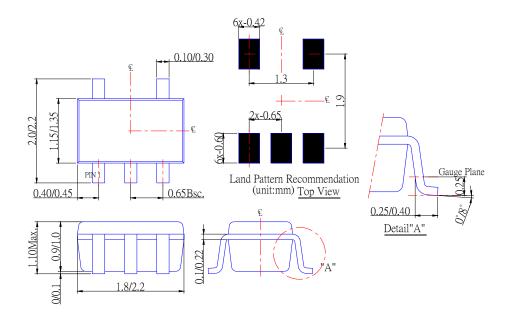


Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



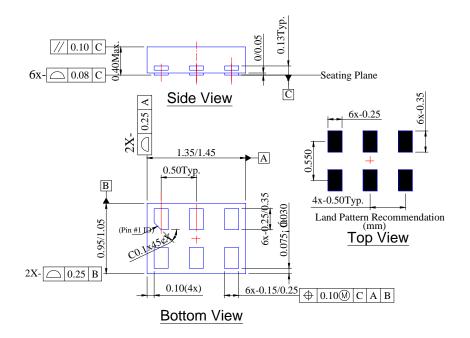
(2) Package Type: SOT353





Package Outline Dimensions (All Dimensions in mm)

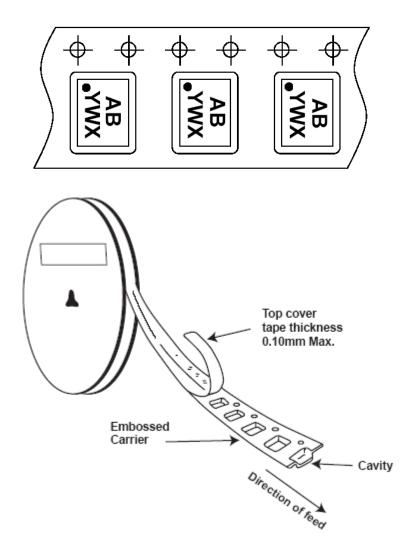
(3) Package Type: DFN1410





Taping Orientation (Note 7)

For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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